

ABSTRACT

[0034] An image sensor camera module includes a dielectric flex tape and a semiconductor die including an imager array. Die attach pads are formed along one edge of the die. The dielectric flex tape overlaps either the top or the bottom of the die, and connections between the die and the tape are made using solder bumps or wire bonds, for example. No supporting substrate other than the tape is required. A lensing structure can be attached directly to the die.